



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



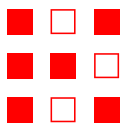
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kester®

Technical Data Sheet

OR-421 Organic-Cored Wire for Lead-free and Lead Alloys

Product Description

Kester OR-421 is a high activity, water-soluble, cored wire flux. The OR-421 is more heat stable, exhibits better wetting capabilities and has less odor than competitive products. The residues left by OR-421 are near neutral pH and therefore also less corrosive. The OR-421 is classified as ORH1 per J-STD-004. Kester OR-421 cored wire solder can be utilized with an open torch or a soldering iron. OR-421 will solder copper as well as more difficult to solder materials such as brass and nickel. OR-421 can be used on pipes or tubing for applications such as refrigeration coils and heat exchangers. The heat stability of Kester OR-421 makes it ideal for high temperature alloys such as Sn95Sb5, Sn63Pb37 and K100LD.

Performance Characteristics:

- Highest activity available
- Compatible with high temperature alloys
- Easy to clean
- Classified as ORH1 per J-STD-004

RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances. (Applies only if this core flux is combined with a lead-free alloy)

Reliability Properties

Copper Mirror Corrosion: High
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Silver Chromate: Fail
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Corrosion Test: High
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Chloride and Bromides: 6.95%
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Availability

OR-421 is available in a wide variety of alloys, wire diameters and flux percentages. For most applications, Sn63Pb37 or Sn96.5Ag3.0Cu0.5 is used. Consult the alloy temperature chart in Kester's product catalog for a comprehensive alloy list. The standard wire diameter for most applications is 1.00mm (0.031in). Wire diameters range from 0.25-6.00mm (0.010-0.250in). A "Standard Wire Diameters" chart also is also included in Kester's product catalog. The amount of flux in the wire dictates the ease of soldering for an application. For most applications, core 66 (3.3% flux by weight) is recommended. Other core sizes, 50 and 58, (1.1% and 2.2% respectively) are available. OR-421 is packaged on spools of different sizes to accommodate a variety of applications.

Process Considerations

Solder iron tip temperatures are most commonly between 315-371°C (600-700°F) for Sn63Pb37 and Sn62Pb36Ag02 alloys and 371-427°C (700-800°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to adding OR-421 cored wire. Apply the solder wire to the land area or component lead. Do not apply the wire directly to the soldering iron tip. If needed, Kester 2331-ZX organic flux may be used as a compatible liquid flux to aid in reworking soldered joints.

Cleaning

OR-421 Flux leaves a residue after soldering that is hygroscopic and ionizable. Removal of ionizable salts can best be accomplished by washing the assembly with a 2-5% solution of Kester 5760 Neutralizer in water, followed by a thorough warm water rinse. The recommended water temperature is $54 \pm 6^\circ\text{C}$ ($130 \pm 10^\circ\text{F}$). If the residue is charred due to excessive heating during soldering, mechanical scrubbing can be used to remove the decomposed char.

Storage and Warranty Period

Storage must be in a dry, non-corrosive environment between 10-40°C (50-104°F). The surface may lose its shine and appear a dull shade of grey. This is a surface phenomenon and is not detrimental to product functionality. Flux-cored solder wire has a limited warranty period determined by the alloy used in the wire. For alloys containing more than 70% lead, the warranty period is 2 years from the date of manufacture. Other alloys have a warranty period of 3 years from the date of manufacture.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet (SDS) and warning label before using this product.